Power Transistor (–60V, –3A)

2SB1184/2SB1243/2SB1185

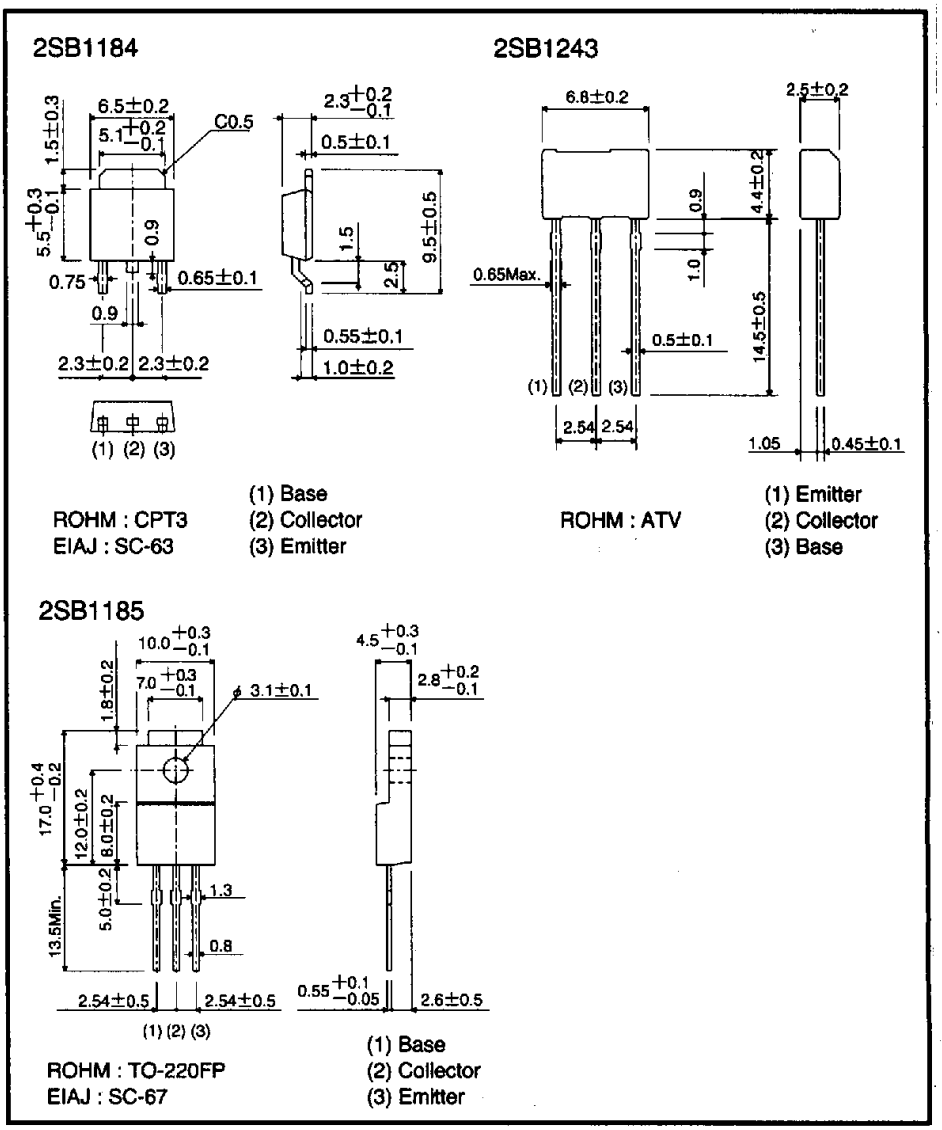
●Features

1) Low $V_{CE(sat)}$.
   $V_{CE(sat)}$ = –0.5V (Typ.)
   (I_C/I_B = –2A/–0.2A)
2) Complements the 2SD1760/2SD1864/2SD1762.

●Structure

Epitaxial planar type
PNP silicon transistor

●External dimensions (Units: mm)



●Absolute maximum ratings (Ta = 25℃)

Parameter		Symbol	Limits	Unit
Collector-base voltage		V_{CBO}	−60	V
Collector-emitter voltage		V_{CEO}	−50	V
Emitter-base voltage		V_{EBO}	−5	V
Collector current		I_C	−3	A (DC)
		I_{CP}	−4.5	A (Pulse) *1
Collector power dissipation	2SB1184	P_C	1	W
			15	W (Tc=25℃)
	2SB1243		1	W *2
	2SB1185		2	
			25	W (Tc=25℃)
Junction temperature		Tj	150	℃
Storage temperature		Tstg	−55~150	℃

*1 Single pulse Pw=100ms
*2 Printed circuit board 1.7mm thick, collector copper plating 1cm² or larger.

●Electrical characteristics (Ta = 25℃)

Parameter		Symbol	Min.	Typ.	Max.	Unit	Conditions
Collector-base breakdown voltage		BV_{CBO}	−60	—	—	V	I_C=−50 μA
Collector-emitter breakdown voltage		BV_{CEO}	−50	—	—	V	I_C=−1mA
Emitter-base breakdown voltage		BV_{EBO}	−5	—	—	V	I_E=−50 μA
Collector cutoff current		I_{CBO}	—	—	−1	μA	V_{CB}=−40V
Emitter cutoff current		I_{EBO}	—	—	−1	μA	V_{EB}=−4V
Collector-emitter saturation voltage		$V_{CE(sat)}$	—	—	−1	V	I_C/I_B=−2A/−0.2A *
Base-emitter saturation voltage		$V_{BE(sat)}$	—	—	−1.5	V	I_C/I_B=−2A/−0.2A *
DC current transfer ratio	2SB1184, 2SB1243	h_{FE}	82	—	390	—	V_{CE}=−3V, I_C=−0.5A *
	2SB1185		60	—	320	—	
Transition frequency		f_T	—	70	—	MHz	V_{CE}=−5V, I_E=0.5A, f=30MHz
Output capacitance		Cob	—	50	—	pF	V_{CB}=−10V, I_E=0A, f=1MHz

* Measured using pulse current.

●Packaging specifications and h_{FE}

Type	h_{FE}	Package	Taping		Bulk
		Code	TL	TV2	—
		Basic ordering unit (pieces)	2500	2500	200
2SB1184	PQR		○	—	—
2SB1243	PQR		—	○	—
2SB1185	DEF		—	—	○

h_{FE} values are classified as follows :

Item	D	E	F
h_{FE}	60~120	100~200	160~320

Item	P	Q	R
h_{FE}	82~180	120~270	180~390

●Electrical characteristic curves

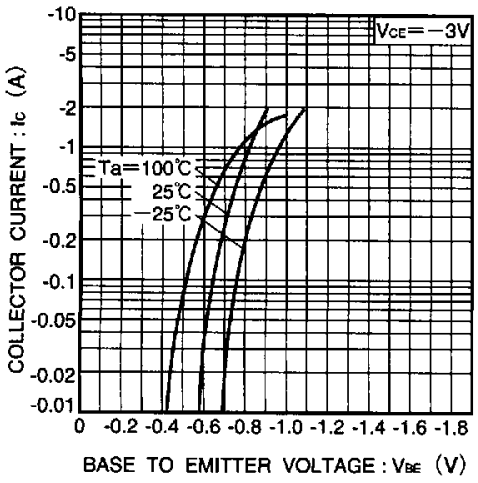


Fig.1 Grounded emitter propagation characteristics

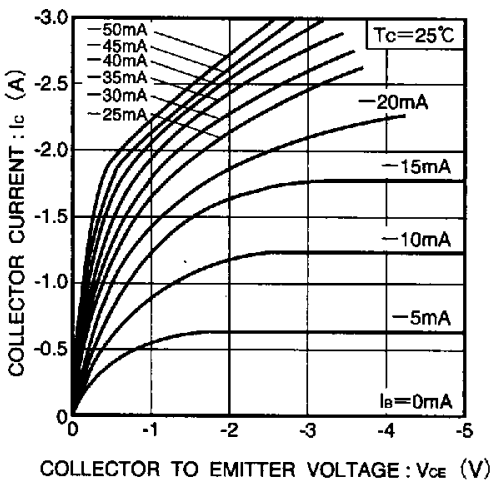


Fig.2 Grounded emitter output characteristics (Ⅰ)

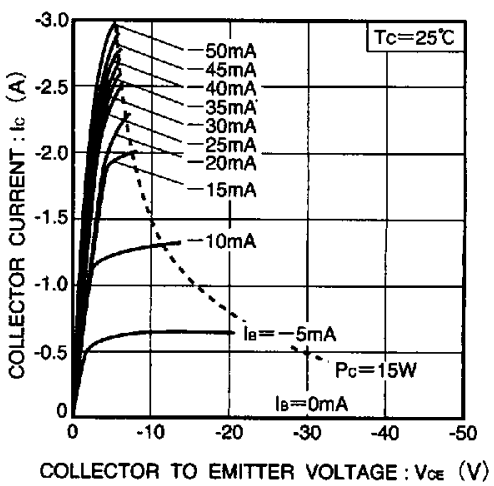


Fig.3 Grounded emitter output characteristics (Ⅱ)

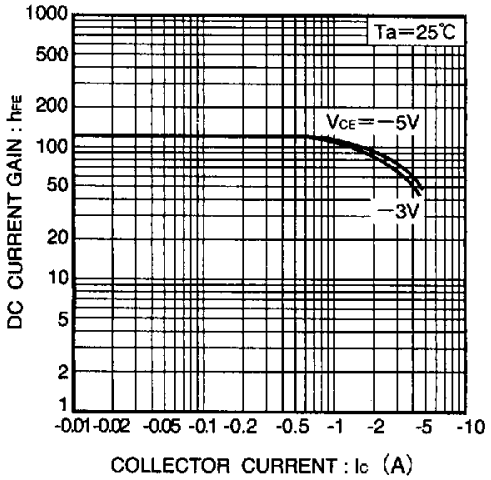


Fig.4 DC current gain vs. collector current (Ⅰ)

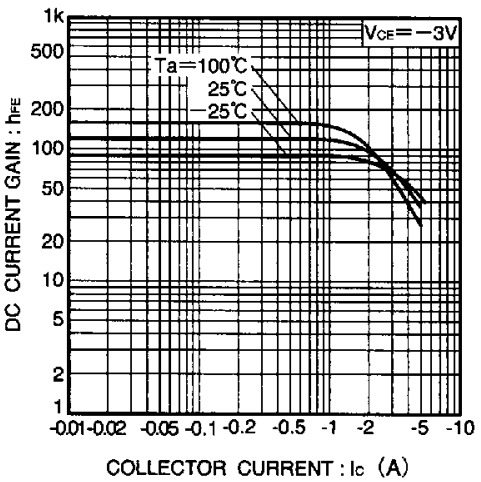


Fig.5 DC current gain vs. collector current (Ⅱ)

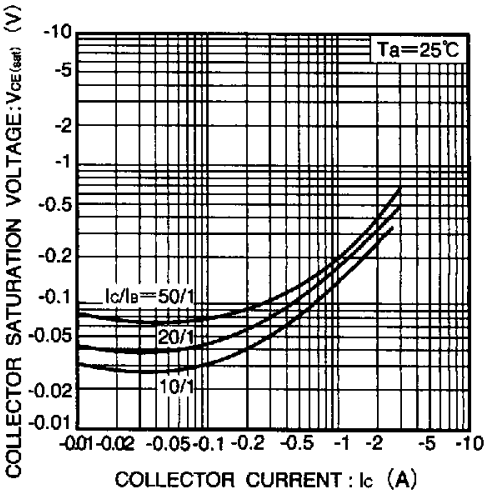


Fig.6 Collector-emitter saturation voltage vs.collector current

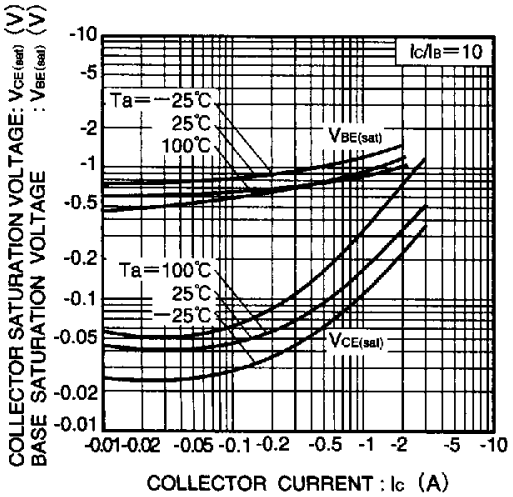


Fig.7 Collector-emitter saturation voltage vs. collector current
Base-emitter saturation voltage vs. collector current

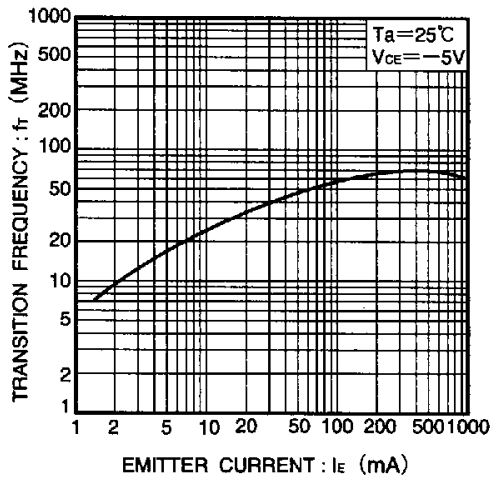


Fig.8 Gain bandwidth product vs. emitter current

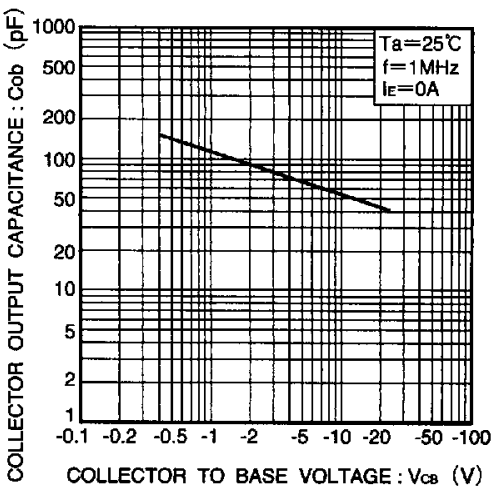


Fig.9 Collector output capacitance vs. collector base voltage

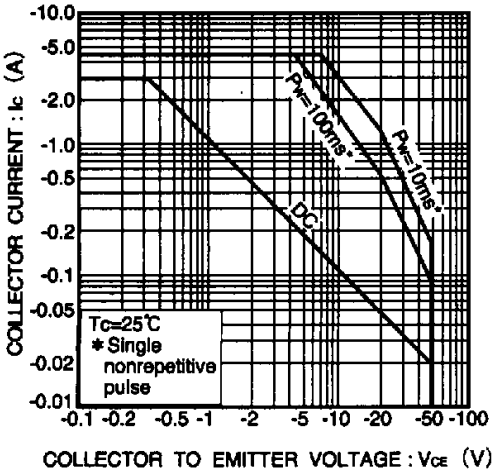


Fig.10 Safe operation area (2SB1184)

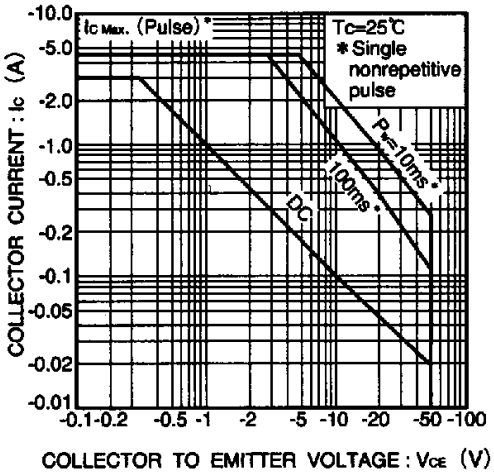


Fig.11 Safe operation area (2SB1243)

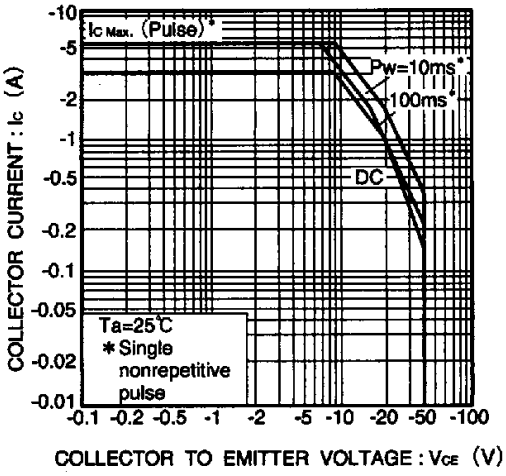
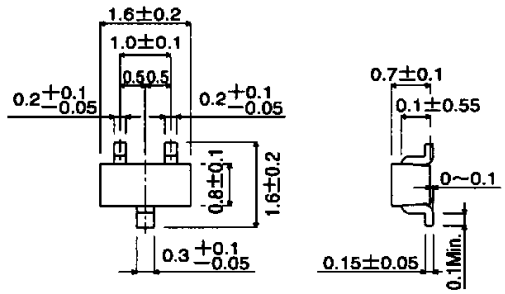
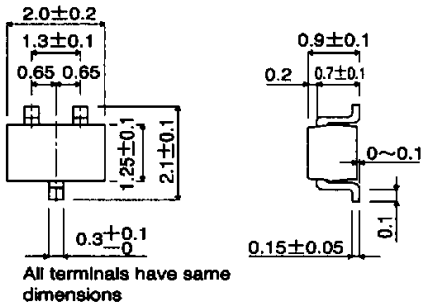
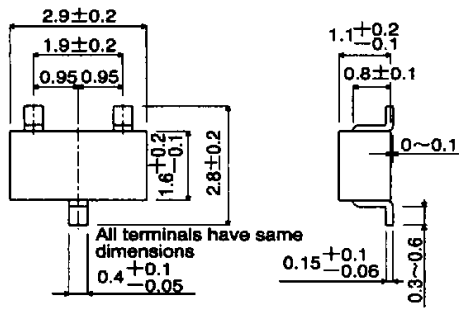
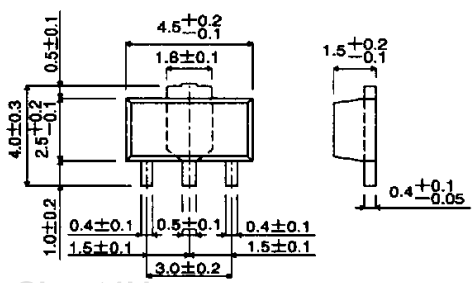


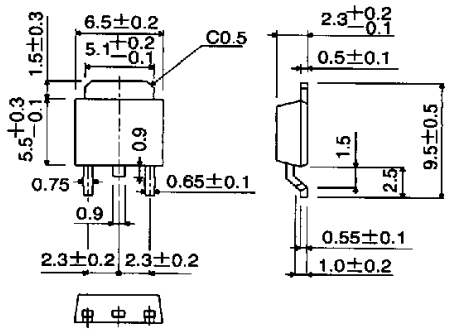
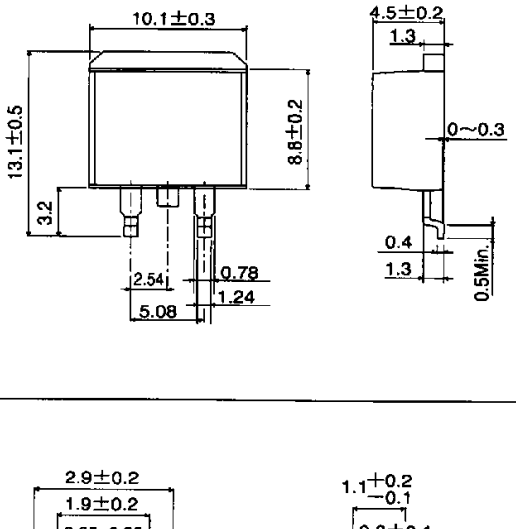
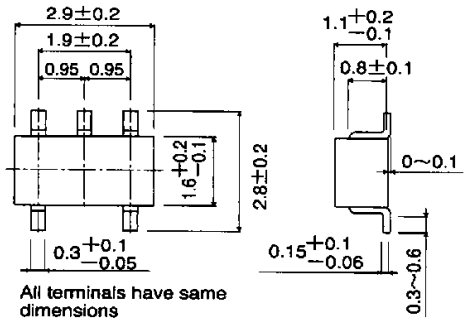
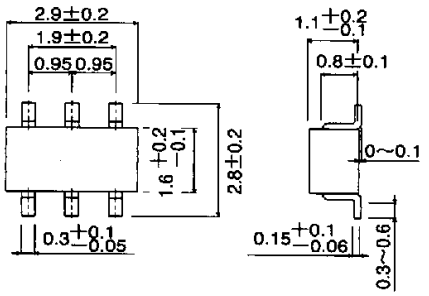
Fig.12 Safe operation area (2SB1185)

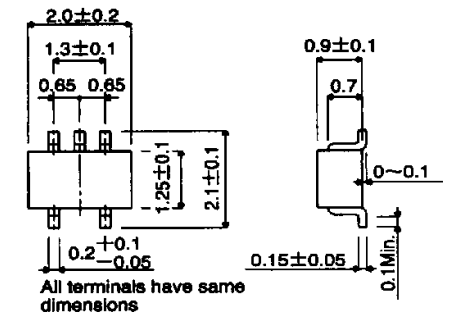
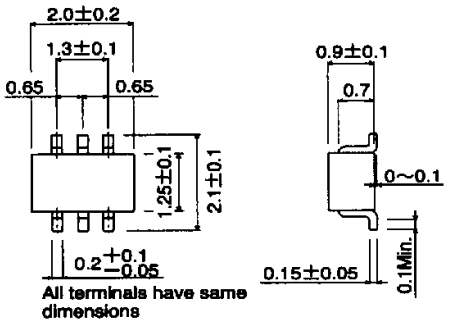
Packages

ROHM has been manufacturing transistors since 1975. In the development of products, we constantly strive to anticipate the needs of our customers. Regarding packages, the demands of the market for compactness, low power consumption, low power dissipation and automatic mounting support are becoming ever greater, and we are strengthening our product development system to meet these needs.

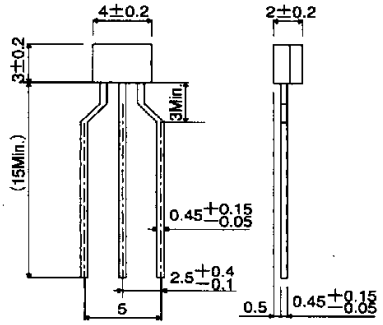
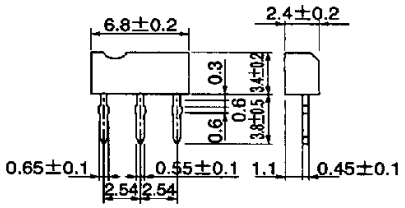
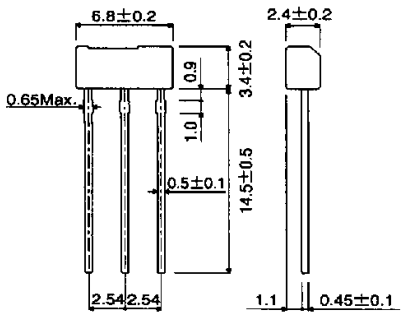
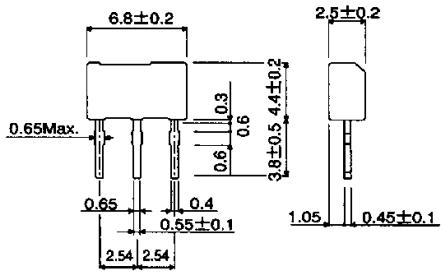
●Types and features of surface-mount packages

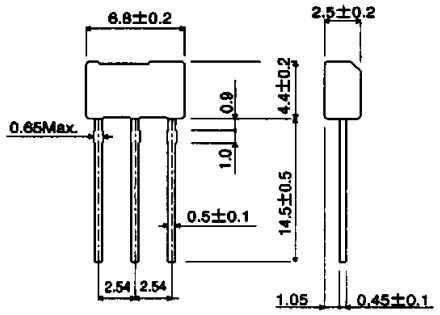
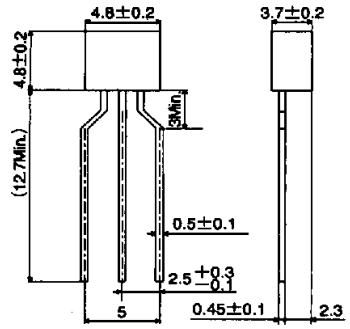
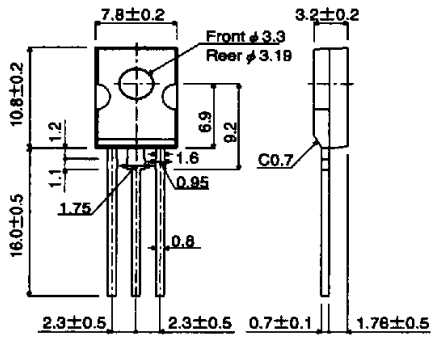
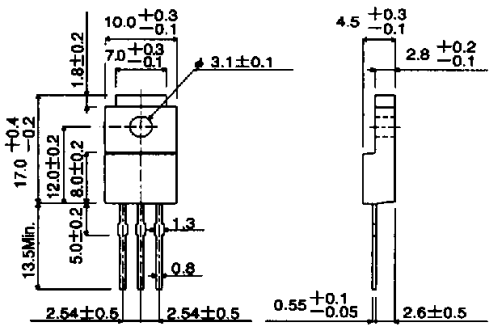
Type	External dimensions (Units : mm)	Features
EMT3 SC-75A type		A more compact version of the UMT3 (SC-70), the EMT3 is the world's smallest transistor with a mold size of 1.6 × 0.8 mm. The mounting area is approximately 60% of the UMT3 and 30% of the SMT3, making it ideal for ultra-high density mounting. Mounting is possible with the same type of automatic mounting machine as the UMT3.
UMT3 SC-70 type		The UMT3 is a smaller version of the SMT3 (SC-59). The mounting area is approximately 60% of the SMT3, making it optimum for high density mounting. The taping size is the same as the SMT3, allowing use of conventional automatic mounting machines. Electrical characteristics and reliability are the same as the SMT3.
SMT3 SC-59 type		The SMT3 is a compact package suitable for small electronic devices and hybrid IC applications. With proven performance, this is one of the most basic small packages. With the exception of Pc (collector power dissipation), electrical characteristics are similar to leaded packages. Reliability is on the same level as the TO-92.
MPT3 SC-62 type		By itself the MPT3 has a Pc of 0.5 W (Ta = 25℃), but when used on a 40 × 40 × 0.7 mm ceramic board, Pc = 2 W (Tc = 25℃), allowing high power to be obtained with a small package. The flat package makes it suitable for applications requiring compactness such as hybrid ICs. Available on tape for automatic mounting.

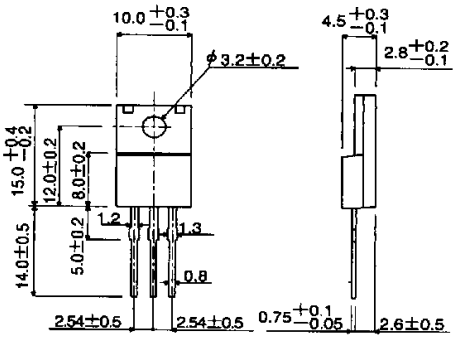
Type	External dimensions (Units : mm)	Features
CPT 3 SC-63 type		By itself the CPT3 has a Pc of 1 W (Ta = 25℃), but a large Pc of several watts can be obtained with an appropriate mounting surface. At the same time the CPT3 is compact, making it suitable for high density mounting and hybrid ICs. Available on tape for automatic mounting. For vertical high density mounting, the leaded CPT (SC-64) type with the same mold size is also available.
PSD3		The PSD3 is a TO-220 class surface-mount package. A high Pc can be obtained with an appropriate mounting surface. Surface mounting allows a high vertical density, enabling the design of slim and compact devices. The PSD3 is available on tape for automatic mounting, and it helps improve mounting efficiency and reduce mounting cost.
SMT5 SC-74A type		The SMT5 consists of two connected transistors or digital transistors in an SMT3 (SC-59) package. The mounting area can be reduced by 50% compared to the SMT3 and the internal circuitry is complete, making this package ideal for high density mounting at half the assembly cost.
SMT6 SC-74 type		The SMT6 consists of two independent transistors or two independent digital transistors in an SMT3 (SC-59) package. The mounting area and mounting cost can be reduced by 50% compared to the SMT3, and the two transistors are independent to allow free configuration of a high density circuit.

Type	External dimensions (Units : mm)	Features
UMT5 SC-88A type		The UMT5 consists of two connected transistors or digital transistors in a UMT3 (SC-70) package. The mounting area can be reduced by 50% compared to the UMT3 and the internal circuitry is completed, making this package ideal for high density mounting at half the assembly cost.
UMT6 SC-88 type		The UMT6 consists of two independent transistors or two independent digital transistors in a UMT (SC-70) package. The mounting area and mounting cost can be reduced by 50% compared to the UMT3, and the two transistors are independent to allow free configuration of a high density circuit.

●Types and features of leaded packages

Type	External dimensions (Units : mm)	Features
SPT (SC-72 type)		The SPT is a smaller version of the conventional TO-92 type. The body size (3×4×2 mm³) has been reduced to 1/4 that of the TO-92 (5×5×4 mm³). The SPT is available on tape for automatic insertion, and less space is occupied on the printed circuit board than the TO-92. Reliability is the same as the TO-92.
FTR		SIL type with a height of 3.4 mm and a lead pitch of 2.54 mm.
FTL		The FTL is a radial taping version of the highly popular FTR. This enables automatic high-density mounting with a radial insertion machine.
ATR (SC-71 type)		SC-71type with a height of 4.4 mm and a P_C=1W type.

Type	External dimensions (Units : mm)	Features
ATV		The ATV is a radial taping version of the highly popular ATR. This enables automatic high-density mounting with a radial insertion machine.
TO-92 (SC-43 type)		The SC-43 is for general purpose small signals.
TO-126FP		The TO-126FP is an isolation type package based on a TO-126 full mold. In addition to the features of the TO-126, molded heat sink fins allow easy isolation of the heat sink.
TO-220FP (SC-67 type)		The TO-220FP is an isolation type package based on a TO-220 full mold. In addition to the features of the TO-126 and TO-220, molded heat sink fins allow easy isolation of the heat sink.

Type	External dimensions (Units : mm)	Features
TO-220FN		The TO-220FN features the same performance as the TO-220FP with approximately 2 mm less height, allowing the design of slimmer devices. Furthermore, the elimination of support pins in the fin (collector electrode) solves short-circuiting problems with neighboring components and the chassis. To make the heigth to the installation hole the same as the TO-220FP, it can be replaced as is from the TO-220FP.